

SN74LV10A トリプル 3 入力正論理 NAND ゲート

1 特長

- 2V~5.5V の V_{CC} で動作
- 最大 t_{pd} 7ns (5V 時)
- 標準 V_{OLP} (出力グランド・バウンス) $< 0.8V$ ($V_{CC} = 3.3V$, $T_A = 25^\circ C$)
- 標準 V_{OHV} (出力 V_{OH} アンダーシュート) $> 2.3V$ ($V_{CC} = 3.3V$, $T_A = 25^\circ C$)
- I_{off} により部分的パワーダウン・モード動作をサポート
- JESD 78, Class II 準拠で 100mA 超のラッチアップ性能

2 アプリケーション

- アラーム / タンパ検出回路
- S-R ラッチ

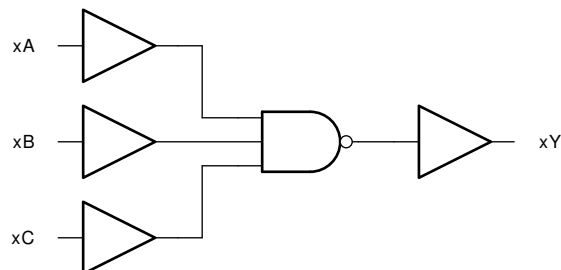
3 説明

これらのトリプル 3 入力正論理 NAND ゲートは、2V~5.5V V_{CC} 動作に向けて設計されています。SN74LV10A デバイスはブール関数 $Y = \overline{A \cdot B \cdot C}$ を正論理で実行します。これらのデバイスは、 I_{off} を使用する部分的パワーダウン・アプリケーション用の動作が完全に規定されています。 I_{off} 回路が出力をディスエーブルにするので、電源切断時にデバイスに電流が逆流して損傷に至ることを回避できます。

パッケージ情報⁽¹⁾

部品番号	パッケージ ⁽¹⁾	本体サイズ (公称)
SN74LV10A	D (SOIC, 14)	8.65mm × 3.90mm
	NS (SO, 14)	10.20mm × 5.30mm
	PW (TSSOP, 14)	5.00mm × 4.40mm

(1) 利用可能なすべてのパッケージについては、このデータシートの末尾にある注文情報を参照してください。



簡略回路図



Table of Contents

1 特長	1	8 Detailed Description	8
2 アプリケーション	1	8.1 Overview.....	8
3 説明	1	8.2 Functional Block Diagram.....	8
4 Revision History	2	8.3 Device Functional Modes.....	8
5 Pin Configuration and Functions	3	9 Application and Implementation	9
6 Specifications	4	9.1 Power Supply Recommendations.....	9
6.1 Absolute Maximum Ratings.....	4	9.2 Layout.....	9
6.2 ESD Ratings.....	4	10 Device and Documentation Support	10
6.3 Recommended Operating Conditions	4	10.1 Documentation Support.....	10
6.4 Thermal Information.....	5	10.2 ドキュメントの更新通知を受け取る方法.....	10
6.5 Electrical Characteristics.....	5	10.3 サポート・リソース.....	10
6.6 Switching Characteristics, $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$	5	10.4 Trademarks.....	10
6.7 Switching Characteristics, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$	6	10.5 静電気放電に関する注意事項.....	10
6.8 Switching Characteristics, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$	6	10.6 用語集.....	10
6.9 Noise Characteristics.....	6	11 Mechanical, Packaging, and Orderable	
6.10 Operating Characteristics.....	6	Information	10
7 Parameter Measurement Information	7		

4 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision F (May 2022) to Revision G (March 2023) Page

- ドキュメントの構造レイアウトを現行の標準に更新、「アプリケーション」セクションを追加、「パッケージ情報」表を更新 1

Changes from Revision E (April 2015) to Revision F (May 2022) Page

- 最新のデータシート規格を反映するように、文書全体にわたって採番方式、書式、表、図、相互参照を更新..... 1

5 Pin Configuration and Functions

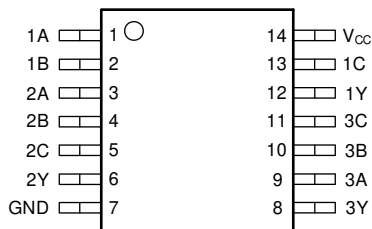


図 5-1. SN74LV10A . . . D, NS, or PW Package (Top View)

表 5-1. Pin Functions

PIN		TYPE ⁽¹⁾	DESCRIPTION
NAME	NO.		
1A	1	I	1A Input
1B	2	I	1B Input
NC	3	—	Not internally connected
1C	4	I	1C Input
1D	5	I	1D Input
1Y	6	O	1Y Output
2Y	8	O	2Y Output
2A	9	I	2A Input
2B	10	I	2B Input
NC	11	—	Not internally connected
2C	12	I	2C Input
2D	13	I	2D Input
GND	7	—	Ground Pin
V _{CC}	14	—	Power Pin

(1) Signal Types: I = Input, O = Output.

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	–0.5	7	V
V_I	Input voltage range ⁽²⁾	–0.5	7	V
V_O	Output voltage range applied in high or low state ^{(2) (3)}	–0.5	$V_{CC} + 0.5$	V
V_O	Output voltage range applied in power-off state ⁽²⁾	–0.5	7	V
I_{IK}	Input clamp current ($V_I < 0$)		–20	mA
I_{OK}	Output clamp current ($V_O < 0$)		–50	mA
I_O	Continuous output current ($V_O = 0$ to V_{CC})		±25	mA
	Continuous current through V_{CC} or GND		±50	mA
θ_{JA}	Package thermal impedance		150	°C
T_{stg}	Storage temperature	–65	150	°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 5.5 V maximum.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	± 2000	V
		Machine Model, per JEDEC specification	± 200	
		Charged device model (CDM), per JEDEC specification JS-002 ⁽²⁾	± 1000	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V_{CC}	Supply voltage	2	5.5	V
V_{IH}	High level input voltage	$V_{CC} = 2$ V	1.5	V
		$V_{CC} = 2.3$ V to 2.7 V	$V_{CC} \times 0.7$	
		$V_{CC} = 3$ V to 3.6 V	$V_{CC} \times 0.7$	
		$V_{CC} = 4.5$ V to 5.5 V	$V_{CC} \times 0.7$	
V_{IL}	Low level input voltage	$V_{CC} = 2$ V	0.5	V
		$V_{CC} = 2.3$ V to 2.7 V	$V_{CC} \times 0.3$	
		$V_{CC} = 3$ V to 3.6 V	$V_{CC} \times 0.3$	
		$V_{CC} = 4.5$ V to 5.5 V	$V_{CC} \times 0.3$	
V_I	Input voltage	0	5.5	V
V_O	Output voltage	0	V_{CC}	V
I_{OH}	High level output current	$V_{CC} = 2$ V	–50	μA
		$V_{CC} = 2.3$ V to 2.7 V	–2	mA
		$V_{CC} = 3$ V to 3.6 V	–6	
		$V_{CC} = 4.5$ V to 5.5 V	–12	

6.3 Recommended Operating Conditions (continued)

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
I_{OL}	Low level output current	$V_{CC} = 2\text{ V}$	50	μA
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	2	mA
		$V_{CC} = 3\text{ V to }3.6\text{ V}$	6	
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	12	
$\Delta t/\Delta v$	Input transition rise and fall rate	$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	200	ns/V
		$V_{CC} = 3\text{ V to }3.6\text{ V}$	100	
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	20	
T_A	Operating free-air temperature	–40	85	$^{\circ}\text{C}$

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#)

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		SN74LV10A			UNIT
		D	NS	PW	
		14 PINS	14 PINS	14 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	86	76	113	$^{\circ}\text{C/W}$

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report ([SPRA953](#)).

6.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
V_{OH}	High-level output voltage	$I_{OH} = -50\text{ }\mu\text{A}$	2 V to 5.5 V	$V_{CC} - 0.1$		V
		$I_{OH} = -2\text{ mA}$	2.3 V	2		
		$I_{OH} = -6\text{ mA}$	3 V	2.48		
		$I_{OH} = -12\text{ mA}$	4.5 V	3.8		
V_{OL}	Low-level output voltage	$I_{OL} = 50\text{ }\mu\text{A}$	2 V to 5.5 V		0.1	V
		$I_{OL} = 2\text{ mA}$	2.3 V		0.4	
		$I_{OL} = 6\text{ mA}$	3 V		0.44	
		$I_{OL} = 12\text{ mA}$	4.5 V		0.55	
I_I	Input leakage current	$V_I = 5.5\text{ V or GND}$	0 to 5.5 V		± 1	μA
I_{CC}	Supply current	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V		20	μA
C_i	Input capacitance	$V_I = V_{CC}$ or GND	3.3 V	1.9		pF

6.6 Switching Characteristics, $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$

over recommended operating free-air temperature range (unless otherwise noted) (see [7-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^{\circ}\text{C}$			SN74LV10A		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A, B, or C	Y	$C_L = 15\text{ pF}$		7.1	13	1	15.5	ns
t_{pd}	A, B, or C	Y	$C_L = 50\text{ pF}$		10.3	17.1	1	20.5	

6.7 Switching Characteristics, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 7-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN74LV10A		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A, B, or C	Y	$C_L = 15\text{ pF}$		5.2	8.4	1	10	ns
t_{pd}	A, B, or C	Y	$C_L = 50\text{ pF}$		7.4	11.9	1	13.5	

6.8 Switching Characteristics, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 7-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN74LV10A		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A, B, or C	Y	$C_L = 15\text{ pF}$		3.9	5.9	1	7	ns
t_{pd}	A, B, or C	Y	$C_L = 50\text{ pF}$		5.4	7.9	1	9	

6.9 Noise Characteristics

$V_{CC} = 3.3\text{ V}$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}$

PARAMETER ⁽¹⁾		MIN	TYP	MAX	UNIT
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}		0.2	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}		0	–0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}		3.2		V
$V_{IH(D)}$	High-level dynamic input voltage	2.31			V
$V_{IL(D)}$	Low-level dynamic input voltage			0.99	V

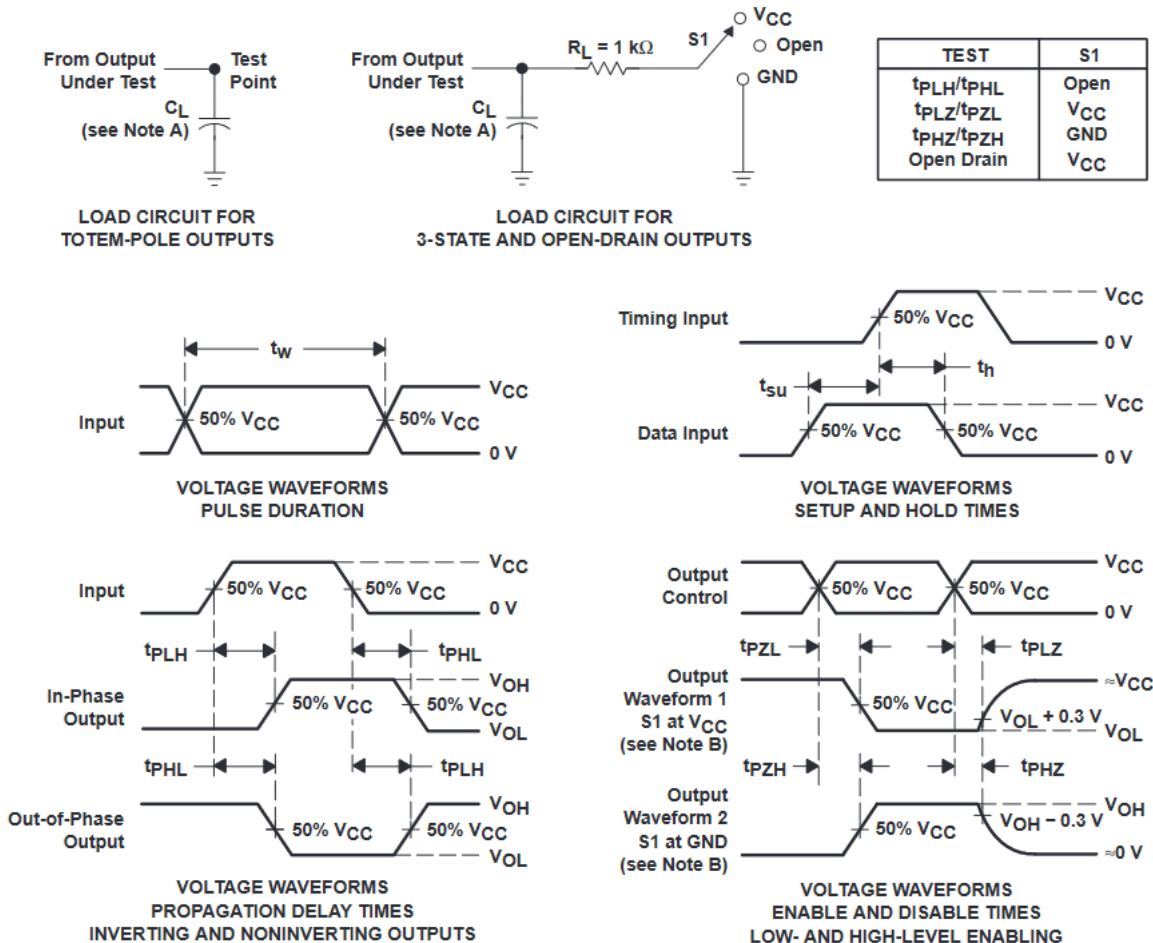
(1) Characteristics are for surface-mount packages only.

6.10 Operating Characteristics

$T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS		V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	$C_L = 50\text{ pF}$, $f = 10\text{ MHz}$		3.3 V	14	pF
				5 V	16.7	

7 Parameter Measurement Information



7-1. Load Circuit and Voltage Waveforms

- A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PHL} and t_{PLH} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

8 Detailed Description

8.1 Overview

These triple 3-input positive-NAND gates are designed for 2-V to 5.5-V V_{CC} operation. The SN74LV10A devices perform the Boolean function $Y = \overline{A \cdot B \cdot C}$ in positive logic. These devices are fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

8.2 Functional Block Diagram

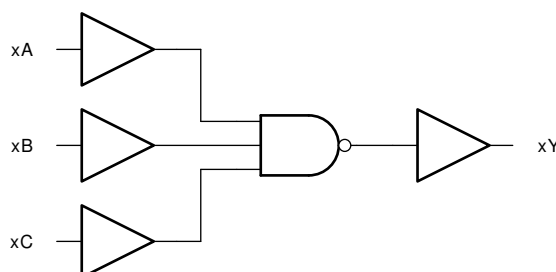


图 8-1. Simplified Schematic

8.3 Device Functional Modes

表 8-1. FUNCTION TABLE
(each gate)

INPUT ⁽¹⁾			OUTPUT ⁽²⁾
A	B	C	Y
H	H	H	L
L	X	X	H
X	L	X	H
X	X	L	H

(1) H = High Voltage Level, L = Low Voltage Level, X = Don't Care

(2) H = Driving High, L = Driving Low

9 Application and Implementation

注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

9.1 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the Recommended Operating Conditions. Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. A 0.1- μ F capacitor is recommended for this device. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. The 0.1- μ F and 1- μ F capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

9.2 Layout

9.2.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices inputs must not ever be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or V_{CC} , whichever makes more sense for the logic function or is more convenient.

10 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

10.1 Documentation Support

10.1.1 Related Documentation

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

表 10-1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN74LV10A	Click here	Click here	Click here	Click here	Click here

10.2 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、ti.com のデバイス製品フォルダを開いてください。「更新の通知を受け取る」をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取れます。変更の詳細については、修正されたドキュメントに含まれている改訂履歴をご覧ください。

10.3 サポート・リソース

[TI E2E™ サポート・フォーラム](#)は、エンジニアが検証済みの回答と設計に関するヒントをエキスパートから迅速かつ直接得ることができる場所です。既存の回答を検索したり、独自の質問をしたりすることで、設計に必要な支援を迅速に得ることができます。

リンクされているコンテンツは、該当する貢献者により、現状のまま提供されるものです。これらは TI の仕様を構成するものではなく、必ずしも TI の見解を反映したものではありません。TI の[使用条件](#)を参照してください。

10.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

すべての商標は、それぞれの所有者に帰属します。

10.5 静電気放電に関する注意事項



この IC は、ESD によって破損する可能性があります。テキサス・インスツルメンツは、IC を取り扱う際には常に適切な注意を払うことを推奨します。正しい取り扱いおよび設置手順に従わない場合、デバイスを破損するおそれがあります。

ESD による破損は、わずかな性能低下からデバイスの完全な故障まで多岐にわたります。精密な IC の場合、パラメータがわずかに変化するだけで公表されている仕様から外れる可能性があるため、破損が発生しやすくなっています。

10.6 用語集

[テキサス・インスツルメンツ用語集](#) この用語集には、用語や略語の一覧および定義が記載されています。

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74LV10AD	Obsolete	Production	SOIC (D) 14	-	-	Call TI	Call TI	-40 to 85	LV10A
SN74LV10ADR	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV10A
SN74LV10ADR.A	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV10A
SN74LV10ADRG4	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV10A
SN74LV10ANSR	Active	Production	SOP (NS) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV10A
SN74LV10ANSR.A	Active	Production	SOP (NS) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV10A
SN74LV10APWR	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	LV10A
SN74LV10APWR.A	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV10A
SN74LV10APWRG4.A	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	No	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV10A
SN74LV10APWRG4.A	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV10A

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative

and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV10ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LV10ANSR	SOP	NS	14	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
SN74LV10APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV10ADR	SOIC	D	14	2500	353.0	353.0	32.0
SN74LV10ANSR	SOP	NS	14	2000	353.0	353.0	32.0
SN74LV10APWR	TSSOP	PW	14	2000	353.0	353.0	32.0

D0014A**PACKAGE OUTLINE****SOIC - 1.75 mm max height**

SMALL OUTLINE INTEGRATED CIRCUIT



4220718/A 09/2016

NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

EXAMPLE BOARD LAYOUT

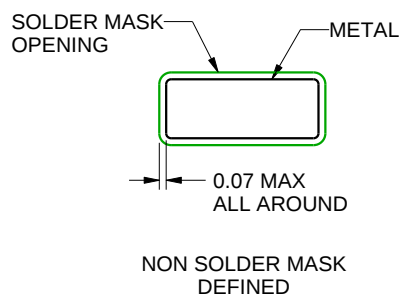
D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

EXAMPLE BOARD LAYOUT

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220202/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

重要なお知らせと免責事項

TI は、技術データと信頼性データ (データシートを含みます)、設計リソース (リファレンス デザインを含みます)、アプリケーションや設計に関する各種アドバイス、Web ツール、安全性情報、その他のリソースを、欠陥が存在する可能性のある「現状のまま」提供しており、商品性および特定目的に対する適合性の黙示保証、第三者の知的財産権の非侵害保証を含むいかなる保証も、明示的または黙示的にかかわらず拒否します。

これらのリソースは、TI 製品を使用する設計の経験を積んだ開発者への提供を意図したものです。(1) お客様のアプリケーションに適した TI 製品の選定、(2) お客様のアプリケーションの設計、検証、試験、(3) お客様のアプリケーションに該当する各種規格や、その他のあらゆる安全性、セキュリティ、規制、または他の要件への確実な適合に関する責任を、お客様のみが単独で負うものとし、TI は一切の責任を拒否します。

上記の各種リソースは、予告なく変更される可能性があります。これらのリソースは、リソースで説明されている TI 製品を使用するアプリケーションの開発の目的でのみ、TI はその使用をお客様に許諾します。これらのリソースに関して、他の目的で複製することや掲載することは禁止されています。TI や第三者の知的財産権のライセンスが付与されている訳ではありません。お客様は、これらのリソースを自身で使用した結果発生するあらゆる申し立て、損害、費用、損失、責任について、TI およびその代理人を完全に補償するものとし、TI は一切の責任を拒否します。

TI の製品は、[TI の販売条件](#)、[TI の総合的な品質ガイドライン](#)、[ti.com](https://www.ti.com) または TI 製品などに関連して提供される他の適用条件に従い提供されます。TI がこれらのリソースを提供することは、適用される TI の保証または他の保証の放棄の拡大や変更を意味するものではありません。TI がカスタム、またはカスタマー仕様として明示的に指定していない限り、TI の製品は標準的なカタログに掲載される汎用機器です。

お客様がいかなる追加条項または代替条項を提案する場合も、TI はそれらに異議を唱え、拒否します。

Copyright © 2025, Texas Instruments Incorporated

最終更新日：2025 年 10 月